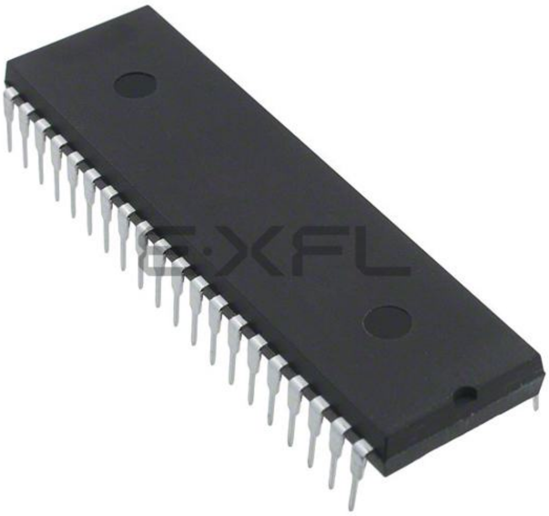
Microchip Technology - PIC16C77-04I/P Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 8x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c77-04i-p

TABLE 1-1: PIC16C7XX FAMILY OF DEVCES

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72(1)
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	1K	2K	2K	—
	ROM Program Memory (14K words)	—	—	—	—	—	2K
	Data Memory (bytes)	36	36	68	128	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/ PWM Module(s)	—	—	—	—	1	1
	Serial Port(s) (SPI/I^{2}C, USART)	—	—	—	—	SPI/I^{2}C	SPI/I^{2}C
	Parallel Slave Port	—	—	—	—	—	—
Features	A/D Converter (8-bit) Channels	4	4	4	4	5	5
	Interrupt Sources	4	4	4	4	8	8
	I/O Pins	13	13	13	13	22	22
	Voltage Range (Volts)	3.0-6.0	3.0-6.0	3.0-6.0	3.0-5.5	2.5-6.0	3.0-5.5
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP

		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20
Memory	EPROM Program Memory (x14 words)	4K	4K	8K	8K
	Data Memory (bytes)	192	192	368	368
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	2	2	2	2
	Serial Port(s) (SPI/I^{2}C, USART)	SPI/I^{2}C, USART	SPI/I^{2}C, USART	SPI/I^{2}C, USART	SPI/I^{2}C, USART
	Parallel Slave Port	—	Yes	—	Yes
	A/D Converter (8-bit) Channels	5	8	5	8
Features	Interrupt Sources	11	12	11	12
	I/O Pins	22	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	Yes	Yes	Yes
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local Microchip sales office for availability of these devices.

4.0 MEMORY ORGANIZATION

Applicable Devices						
72	73	73A	74	74A	76	77

4.1 Program Memory Organization

The PIC16C7X family has a 13-bit program counter capable of addressing an 8K x 14 program memory space. The amount of program memory available to each device is listed below:

Device	Program Memory	Address Range
PIC16C72	2K x 14	0000h-07FFh
PIC16C73	4K x 14	0000h-0FFFh
PIC16C73A	4K x 14	0000h-0FFFh
PIC16C74	4K x 14	0000h-0FFFh
PIC16C74A	4K x 14	0000h-0FFFh
PIC16C76	8K x 14	0000h-1FFFh
PIC16C77	8K x 14	0000h-1FFFh

For those devices with less than 8K program memory, accessing a location above the physically implemented address will cause a wraparound.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 4-1: PIC16C72 PROGRAM MEMORY MAP AND STACK

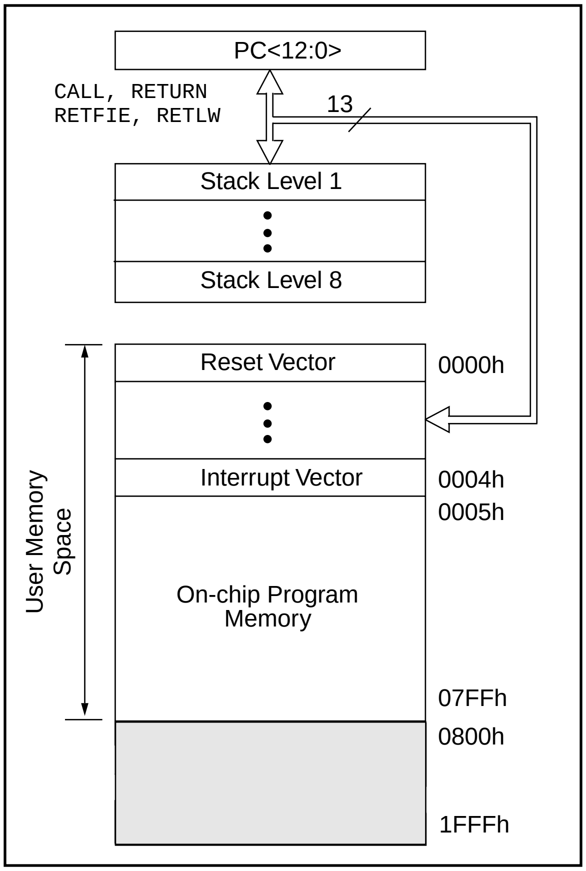
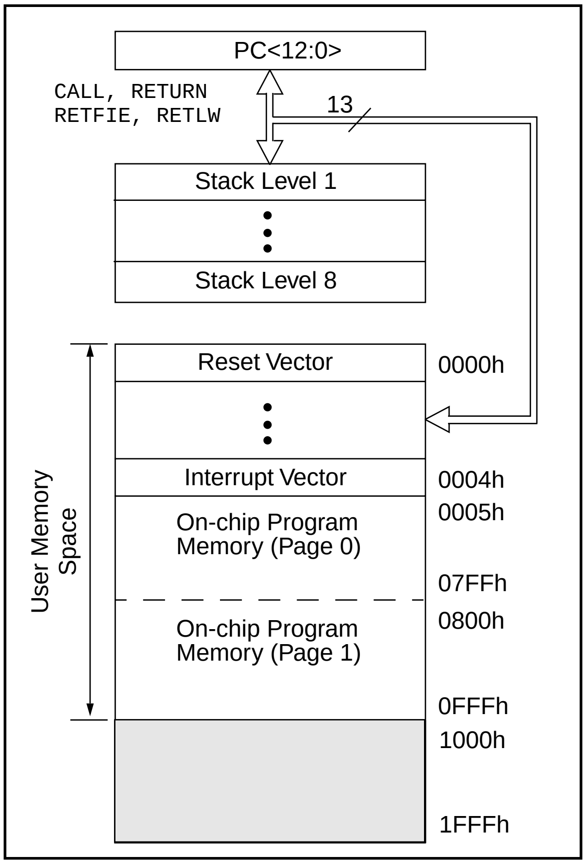


FIGURE 4-2: PIC16C73/73A/74/74A PROGRAM MEMORY MAP AND STACK



5.3 PORTC and TRISC Registers

Applicable Devices						
72	73	73A	74	74A	76	77

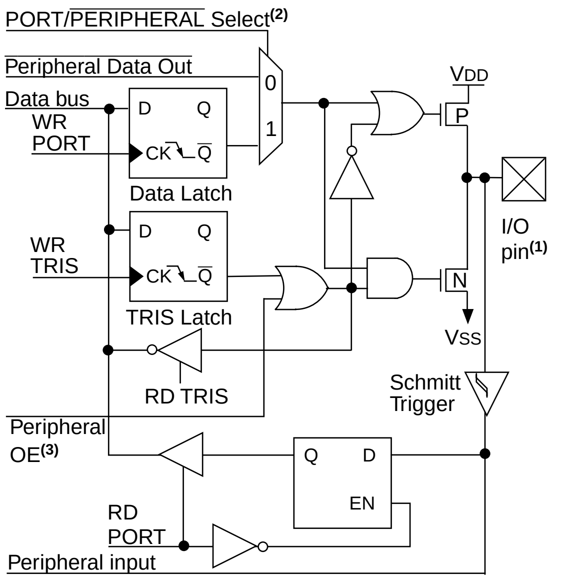
PORTC is an 8-bit bi-directional port. Each pin is individually configurable as an input or output through the TRISC register. PORTC is multiplexed with several peripheral functions (Table 5-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (`BSF, BCF, XORWF`) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

EXAMPLE 5-3: INITIALIZING PORTC

```
BCF    STATUS, RP0  ; Select Bank 0
BCF    STATUS, RP1  ; PIC16C76/77 only
CLRF   PORTC        ; Initialize PORTC by
                    ; clearing output
                    ; data latches
BSF    STATUS, RP0  ; Select Bank 1
MOVLW  0xCF         ; Value used to
                    ; initialize data
                    ; direction
MOVWF  TRISC        ; Set RC<3:0> as inputs
                    ; RC<5:4> as outputs
                    ; RC<7:6> as inputs
```

FIGURE 5-6: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE)



Note 1: I/O pins have diode protection to VDD and VSS.
2: Port/Peripheral select signal selects between port data and peripheral output.
3: Peripheral OE (output enable) is only activated if peripheral select is active.

TABLE 5-5: PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input
RC1/T1OSI/CCP2(1)	bit1	ST	Input/output port pin or Timer1 oscillator input or Capture2 input/ Compare2 output/PWM2 output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output
RC6/TX/CK(2)	bit6	ST	Input/output port pin or USART Asynchronous Transmit, or USART Synchronous Clock
RC7/RX/DT(2)	bit7	ST	Input/output port pin or USART Asynchronous Receive, or USART Synchronous Data

Legend: ST = Schmitt Trigger input
Note 1: The CCP2 multiplexed function is not enabled on the PIC16C72.
2: The TX/CK and RX/DT multiplexed functions are not enabled on the PIC16C72.

5.5 PORTE and TRISE Register

Applicable Devices						
72	73	73A	74	74A	76	77

PORTE has three pins RE0/$\overline{\text{RD}}$/AN5, RE1/$\overline{\text{WR}}$/AN6 and RE2/$\overline{\text{CS}}$/AN7, which are individually configurable as inputs or outputs. These pins have Schmitt Trigger input buffers.

I/O PORTE becomes control inputs for the microprocessor port when bit PSPMODE (TRISE<4>) is set. In this mode, the user must make sure that the TRISE<2:0> bits are set (pins are configured as digital inputs) and that register ADCON1 is configured for digital I/O. In this mode the input buffers are TTL.

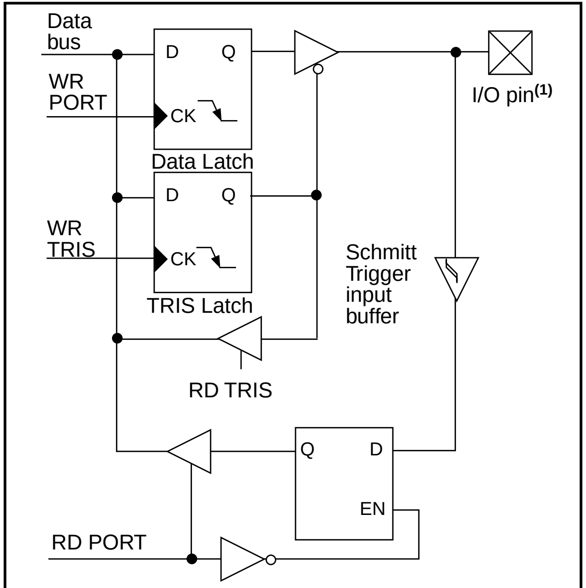
Figure 5-9 shows the TRISE register, which also controls the parallel slave port operation.

PORTE pins are multiplexed with analog inputs. The operation of these pins is selected by control bits in the ADCON1 register. When selected as an analog input, these pins will read as '0's.

TRISE controls the direction of the RE pins, even when they are being used as analog inputs. The user must make sure to keep the pins configured as inputs when using them as analog inputs.

Note: On a Power-on Reset these pins are configured as analog inputs.

FIGURE 5-8: PORTE BLOCK DIAGRAM (IN I/O PORT MODE)



Note 1: I/O pins have protection diodes to V_{DD} and V_{SS}.

FIGURE 5-9: TRISE REGISTER (ADDRESS 89h)

R-0	R-0	R/W-0	R/W-0	U-0	R/W-1	R/W-1	R/W-1
IBF	OBF	IBOV	PSPMODE	—	bit2	bit1	bit0

bit7 bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7 : **IBF:** Input Buffer Full Status bit
1 = A word has been received and is waiting to be read by the CPU
0 = No word has been received

bit 6: **OBF**: Output Buffer Full Status bit
1 = The output buffer still holds a previously written word
0 = The output buffer has been read

bit 5: **IBOV**: Input Buffer Overflow Detect bit (in microprocessor mode)
1 = A write occurred when a previously input word has not been read (must be cleared in software)
0 = No overflow occurred

bit 4: **PSPMODE**: Parallel Slave Port Mode Select bit
1 = Parallel slave port mode
0 = General purpose I/O mode

bit 3: **Unimplemented**: Read as '0'

PORTE Data Direction Bits

bit 2: **Bit2**: Direction Control bit for pin RE2/$\overline{\text{CS}}$/AN7
1 = Input
0 = Output

bit 1: **Bit1**: Direction Control bit for pin RE1/$\overline{\text{WR}}$/AN6
1 = Input
0 = Output

bit 0: **Bit0**: Direction Control bit for pin RE0/$\overline{\text{RD}}$/AN5
1 = Input
0 = Output

8.3 Timer1 Operation in Asynchronous Counter Mode

Applicable Devices						
72	73	73A	74	74A	76	77

If control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during SLEEP and can generate an interrupt on overflow which will wake-up the processor. However, special precautions in software are needed to read/write the timer (Section 8.3.2).

In asynchronous counter mode, Timer1 can not be used as a time-base for capture or compare operations.

8.3.1 EXTERNAL CLOCK INPUT TIMING WITH UNSYNCHRONIZED CLOCK

If control bit $\overline{\text{T1SYNC}}$ is set, the timer will increment completely asynchronously. The input clock must meet certain minimum high time and low time requirements. Refer to the appropriate Electrical Specifications Section, timing parameters 45, 46, and 47.

8.3.2 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running, from an external asynchronous clock, will guarantee a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself poses certain problems since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. Example 8-1 is an example routine to read the 16-bit timer value. This is useful if the timer cannot be stopped.

EXAMPLE 8-1: READING A 16-BIT FREE-RUNNING TIMER

```
; All interrupts are disabled
   MOVF   TMR1H, W  ;Read high byte
   MOVWF  TMPH      ;
   MOVF   TMR1L, W  ;Read low byte
   MOVWF  TMPL      ;
   MOVF   TMR1H, W  ;Read high byte
   SUBWF  TMPH,  W  ;Sub 1st read
                    ; with 2nd read
   BTFSC  STATUS,Z  ;Is result = 0
   GOTO   CONTINUE  ;Good 16-bit read
;
; TMR1L may have rolled over between the read
; of the high and low bytes. Reading the high
; and low bytes now will read a good value.
;
   MOVF   TMR1H, W  ;Read high byte
   MOVWF  TMPH      ;
   MOVF   TMR1L, W  ;Read low byte
   MOVWF  TMPL      ;
; Re-enable the Interrupt (if required)
CONTINUE            ;Continue with your code
```

8.4 Timer1 Oscillator

Applicable Devices						
72	73	73A	74	74A	76	77

A crystal oscillator circuit is built in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low power oscillator rated up to 200 kHz. It will continue to run during SLEEP. It is primarily intended for a 32 kHz crystal. Table 8-1 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must provide a software time delay to ensure proper oscillator start-up.

TABLE 8-1: CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

<table>
<tr><th>Osc Type</th><th>Freq</th><th>C1</th><th>C2</th></tr>
<tr><td rowspan="3">LP</td><td>32 kHz</td><td>33 pF</td><td>33 pF</td></tr>
<tr><td>100 kHz</td><td>15 pF</td><td>15 pF</td></tr>
<tr><td>200 kHz</td><td>15 pF</td><td>15 pF</td></tr>
<tr><td colspan="4">These values are for design guidance only.</td></tr>
<tr><td colspan="4">Crystals Tested:</td></tr>
<tr><td>32.768 kHz</td><td colspan="2">Epson C-001R32.768K-A</td><td>± 20 PPM</td></tr>
<tr><td>100 kHz</td><td colspan="2">Epson C-2 100.00 KC-P</td><td>± 20 PPM</td></tr>
<tr><td>200 kHz</td><td colspan="2">STD XTL 200.000 kHz</td><td>± 20 PPM</td></tr>
<tr><td colspan="4">Note 1: Higher capacitance increases the stability of oscillator but also increases the start-up time.
2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.</td></tr>
</table>

10.0 CAPTURE/COMPARE/PWM MODULE(s)

Applicable Devices							
72	73	73A	74	74A	76	77	**CCP1**
72	73	73A	74	74A	76	77	**CCP2**

Each CCP (Capture/Compare/PWM) module contains a 16-bit register which can operate as a 16-bit capture register, as a 16-bit compare register or as a PWM master/slave Duty Cycle register. Both the CCP1 and CCP2 modules are identical in operation, with the exception of the operation of the special event trigger. Table 10-1 and Table 10-2 show the resources and interactions of the CCP module(s). In the following sections, the operation of a CCP module is described with respect to CCP1. CCP2 operates the same as CCP1, except where noted.

CCP1 module:

Capture/Compare/PWM Register1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. All are readable and writable.

CCP2 module:

Capture/Compare/PWM Register2 (CCPR2) is comprised of two 8-bit registers: CCPR2L (low byte) and CCPR2H (high byte). The CCP2CON register controls the operation of CCP2. All are readable and writable.

For use of the CCP modules, refer to the Embedded Control Handbook, *"Using the CCP Modules"* (AN594).

TABLE 10-1: CCP MODE - TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

TABLE 10-2: INTERACTION OF TWO CCP MODULES

CCPx Mode	CCPy Mode	Interaction
Capture	Capture	Same TMR1 time-base.
Capture	Compare	The compare should be configured for the special event trigger, which clears TMR1.
Compare	Compare	The compare(s) should be configured for the special event trigger, which clears TMR1.
PWM	PWM	The PWMs will have the same frequency, and update rate (TMR2 interrupt).
PWM	Capture	None
PWM	Compare	None

13.4 A/D Conversions

Applicable Devices						
72	73	73A	74	74A	76	77

Example 13-2 shows how to perform an A/D conversion. The RA pins are configured as analog inputs. The analog reference (V_{REF}) is the device V_{DD}. The A/D interrupt is enabled, and the A/D conversion clock is F_{RC}. The conversion is performed on the RA0 pin (channel 0).

Note: The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The ADRES register will NOT be updated with the partially completed A/D conversion sample. That is, the ADRES register will continue to contain the value of the last completed conversion (or the last value written to the ADRES register). After the A/D conversion is aborted, a $2T_{AD}$ wait is required before the next acquisition is started. After this $2T_{AD}$ wait, an acquisition is automatically started on the selected channel.

EXAMPLE 13-2: A/D CONVERSION

```
     BSF     STATUS, RP0         ; Select Bank 1
     BCF     STATUS, RP1         ; PIC16C76/77 only
     CLRF    ADCON1              ; Configure A/D inputs
     BSF     PIE1,   ADIE        ; Enable A/D interrupts
     BCF     STATUS, RP0         ; Select Bank 0
     MOVLW   0xC1                ; RC Clock, A/D is on, Channel 0 is selected
     MOVWF   ADCON0              ;
     BCF     PIR1,   ADIF        ; Clear A/D interrupt flag bit
     BSF     INTCON, PEIE        ; Enable peripheral interrupts
     BSF     INTCON, GIE         ; Enable all interrupts
;
;  Ensure that the required sampling time for the selected input channel has elapsed.
;  Then the conversion may be started.
;
     BSF     ADCON0, GO          ; Start A/D Conversion
       :                         ; The ADIF bit will be set and the GO/DONE bit
       :                         ;  is cleared upon completion of the A/D Conversion.
```

13.8 Use of the CCP Trigger

Applicable Devices						
72	73	73A	74	74A	76	77

Note: In the PIC16C72, the "special event trigger" is implemented in the CCP1 module.

An A/D conversion can be started by the “special event trigger” of the CCP2 module (CCP1 on the PIC16C72 only). This requires that the CCP2M3:CCP2M0 bits (CCP2CON<3:0>) be programmed as `1011` and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D conversion, and the Timer1 counter will be reset to zero. Timer1 is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving the ADRES to the desired location). The appropriate analog input channel must be selected and the minimum acquisition done before the “special event trigger” sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), then the “special event trigger” will be ignored by the A/D module, but will still reset the Timer1 counter.

13.9 Connection Considerations

Applicable Devices						
72	73	73A	74	74A	76	77

If the input voltage exceeds the rail values (VSS or VDD) by greater than 0.2V, then the accuracy of the conversion is out of specification.

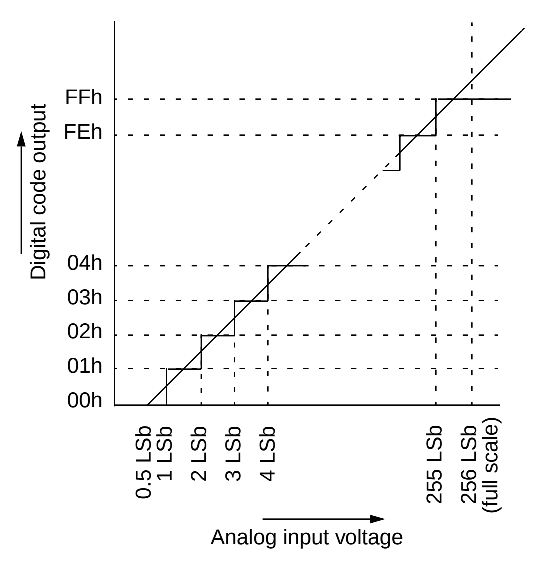
An external RC filter is sometimes added for anti-aliasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 10 kΩ recommended specification. Any external components connected (via hi-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

13.10 Transfer Function

Applicable Devices						
72	73	73A	74	74A	76	77

The ideal transfer function of the A/D converter is as follows: the first transition occurs when the analog input voltage (VAIN) is Analog VREF/256 (Figure 13-5).

FIGURE 13-5: A/D TRANSFER FUNCTION



13.11 References

A very good reference for understanding A/D converters is the "Analog-Digital Conversion Handbook" third edition, published by Prentice Hall (ISBN 0-13-03-2848-0).

FIGURE 14-2: CONFIGURATION WORD FOR PIC16C72/73A/74A/76/77

CP1	CP0	CP1	CP0	CP1	CP0	—	BODEN	CP1	CP0	$\overline{\text{PWRTE}}$	WDTE	FOSC1	FOSC0
bit13													bit0

Register: CONFIG
Address 2007h

bit 13-8 **CP1:CP0**: Code Protection bits (2)
5-4:
`11` = Code protection off
`10` = Upper half of program memory code protected
`01` = Upper 3/4th of program memory code protected
`00` = All memory is code protected

bit 7: **Unimplemented**: Read as '1'

bit 6: **BODEN**: Brown-out Reset Enable bit (1)
1 = BOR enabled
0 = BOR disabled

bit 3: **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit (1)
1 = PWRT disabled
0 = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
`11` = RC oscillator
`10` = HS oscillator
`01` = XT oscillator
`00` = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the CP1:CP0 pairs have to be given the same value to enable the code protection scheme listed.

TABLE 14-6: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C72/73A/74A/76/77

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	x	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
1	0	x	x	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
1	1	1	0	$\overline{\text{MCLR}}$ Reset during SLEEP or interrupt wake-up from SLEEP

TABLE 14-7: RESET CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register PIC16C73/74	PCON Register PIC16C72/73A/74A/76/77
Power-on Reset	000h	0001 1xxx	---- --0-	---- --0x
$\overline{\text{MCLR}}$ Reset during normal operation	000h	000u uuuu	---- --u-	---- --uu
$\overline{\text{MCLR}}$ Reset during SLEEP	000h	0001 0uuu	---- --u-	---- --uu
WDT Reset	000h	0000 1uuu	---- --u-	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --u-	---- --uu
Brown-out Reset	000h	0001 1uuu	N/A	---- --u0
Interrupt wake-up from SLEEP	PC + 1(1)	uuu1 0uuu	---- --u-	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.
Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

TABLE 14-8: INITIALIZATION CONDITIONS FOR ALL REGISTERS

Register	Applicable Devices							Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets WDT Reset	Wake-up via WDT or Interrupt
W	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	72	73	73A	74	74A	76	77	N/A	N/A	N/A
TMR0	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	72	73	73A	74	74A	76	77	0000h	0000h	PC + 1(2)
STATUS	72	73	73A	74	74A	76	77	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	72	73	73A	74	74A	76	77	--0x 0000	--0u 0000	--uu uuuu
PORTB	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTD	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTE	72	73	73A	74	74A	76	77	---- -xxx	---- -uuu	---- -uuu
PCLATH	72	73	73A	74	74A	76	77	---0 0000	---0 0000	---u uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition
Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).
2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).
3: See Table 14-7 for reset value for specific condition.

14.8 Power-down Mode (SLEEP)

Applicable Devices						
72	73	73A	74	74A	76	77

Power-down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{\text{PD}}$ bit (STATUS<3>) is cleared, the $\overline{\text{TO}}$ (STATUS<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before the `SLEEP` instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either V_{DD}, or V_{SS}, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D, disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{\text{MCLR}}$ pin must be at a logic high level (V_{IHMC}).

14.8.1 WAKE-UP FROM SLEEP

The device can wake up from SLEEP through one of the following events:

1. External reset input on $\overline{\text{MCLR}}$ pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from INT pin, RB port change, or some Peripheral Interrupts.

External $\overline{\text{MCLR}}$ Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register can be used to determine the cause of device reset. The $\overline{\text{PD}}$ bit, which is set on power-up, is cleared when `SLEEP` is invoked. The $\overline{\text{TO}}$ bit is cleared if a WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
2. SSP (Start/Stop) bit detect interrupt.
3. SSP transmit or receive in slave mode (SPI/I^{2}C).
4. CCP capture mode interrupt.
5. Parallel Slave Port read or write.
6. A/D conversion (when A/D clock source is RC).
7. Special event trigger (Timer1 in asynchronous mode using an external clock).
8. USART TX or RX (synchronous slave mode).

Other peripherals cannot generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

14.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

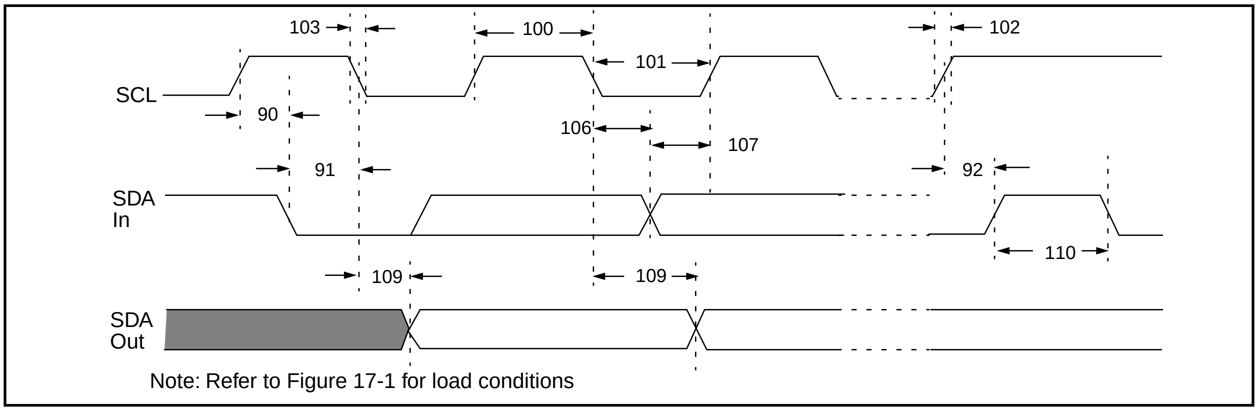
- If the interrupt occurs **before** the execution of a `SLEEP` instruction, the `SLEEP` instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{\text{TO}}$ bit will not be set and $\overline{\text{PD}}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a `SLEEP` instruction, the device will immediately wake up from sleep. The `SLEEP` instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{\text{TO}}$ bit will be set and the $\overline{\text{PD}}$ bit will be cleared.

Even if the flag bits were checked before executing a `SLEEP` instruction, it may be possible for flag bits to become set before the `SLEEP` instruction completes. To determine whether a `SLEEP` instruction executed, test the $\overline{\text{PD}}$ bit. If the $\overline{\text{PD}}$ bit is set, the `SLEEP` instruction was executed as a NOP.

To ensure that the WDT is cleared, a `CLRWDT` instruction should be executed before a `SLEEP` instruction.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 17-10: I^{2}C BUS DATA TIMING



Note: Refer to Figure 17-1 for load conditions

TABLE 17-9: I^{2}C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock high time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101	TLOW	Clock low time	100 kHz mode	4.7	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
103	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
90	TSU:STA	START condition setup time	100 kHz mode	4.7	—	µs	Only relevant for repeated START condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	START condition hold time	100 kHz mode	4.0	—	µs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output valid from clock	100 kHz mode	—	3500	ns	Note 1
			400 kHz mode	—	—	ns	
110	TBUF	Bus free time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast-mode (400 kHz) I^{2}C-bus device can be used in a standard-mode (100 kHz)S I^{2}C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I^{2}C bus specification) before the SCL line is released.

Applicable Devices	72	73	73A	74	74A	76	77

18.0 ELECTRICAL CHARACTERISTICS FOR PIC16C73/74

Absolute Maximum Ratings †

Ambient temperature under bias	-55 to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{MCLR}$. and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3 to +7.5V
Voltage on $\overline{MCLR}$ with respect to VSS (Note 2)	0 to +14V
Voltage on RA4 with respect to Vss	0 to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, IIK (VI < 0 or VI > VDD)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined) (Note 3)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined) (Note 3)	200 mA
Maximum current sunk by PORTC and PORTD (combined) (Note 3)	200 mA
Maximum current sourced by PORTC and PORTD (combined) (Note 3)	200 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

Note 2: Voltage spikes below VSS at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{MCLR}$ pin rather than pulling this pin directly to VSS.

Note 3: PORTD and PORTE are not implemented on the PIC16C73.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

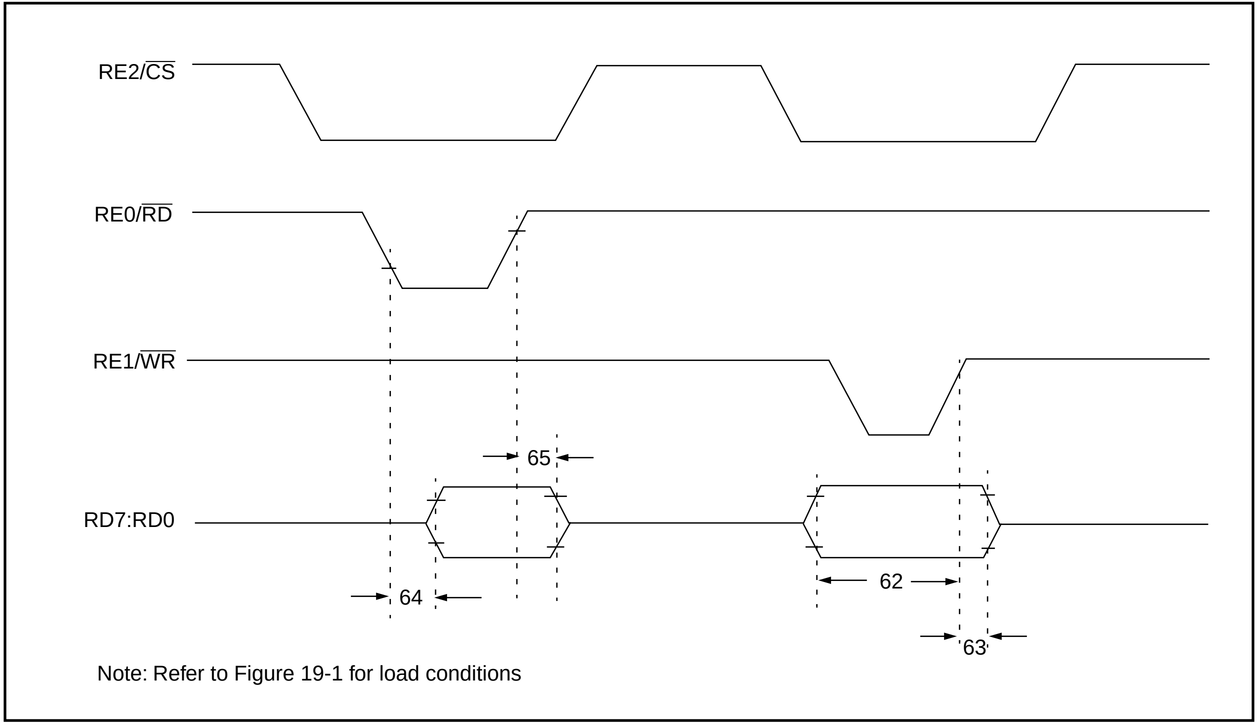
TABLE 18-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C73-04 PIC16C74-04	PIC16C73-10 PIC16C74-10	PIC16C73-20 PIC16C74-20	PIC16LC73-04 PIC16LC74-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 13.5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 13.5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 15 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 µA typ. at 32 kHz, 4.0V IPD: 0.9 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 13.5 µA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 13.5 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications.
It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 19-8: PARALLEL SLAVE PORT TIMING (PIC16C74A)



Note: Refer to Figure 19-1 for load conditions

TABLE 19-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C74A)

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before $\overline{\text{WR}}$↑ or $\overline{\text{CS}}$↑ (setup time)		20 25	— —	— —	ns ns	 Extended Range Only
63*	TwrH2dtI	$\overline{\text{WR}}$↑ or $\overline{\text{CS}}$↑ to data–in invalid (hold time)	PIC16**C**74A	20	—	—	ns	
			PIC16**LC**74A	35	—	—	ns	
64	TrdL2dtV	$\overline{\text{RD}}$↓ and $\overline{\text{CS}}$↓ to data–out valid		— —	— —	80 90	ns ns	 Extended Range Only
65	TrdH2dtI	$\overline{\text{RD}}$↑ or $\overline{\text{CS}}$↓ to data–out invalid		10	—	30	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	72	73	73A	74	74A	76	77

TABLE 20-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C76-04 PIC16C77-04	PIC16C76-10 PIC16C77-10	PIC16C76-20 PIC16C77-20	PIC16LC76-04 PIC16LC77-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 10 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 µA typ. at 32 kHz, 4.0V IPD: 0.9 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 5.0 µA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 5.0 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications.
It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices	72	73	73A	74	74A	76	77

TABLE 20-8: SPI MODE REQUIREMENTS

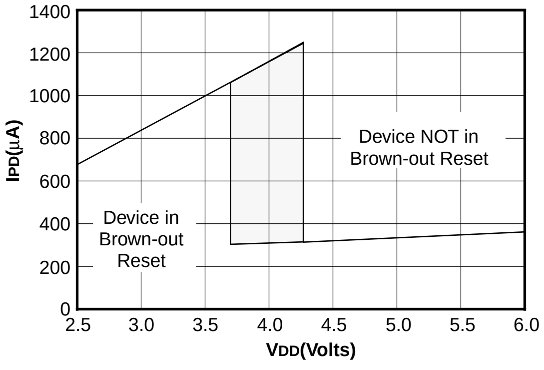
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{\text{SS}}$↓ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{\text{SS}}$↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	TCY	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{\text{SS}}$↓ edge	—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{\text{SS}}$ ↑ after SCK edge	1.5TCY + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

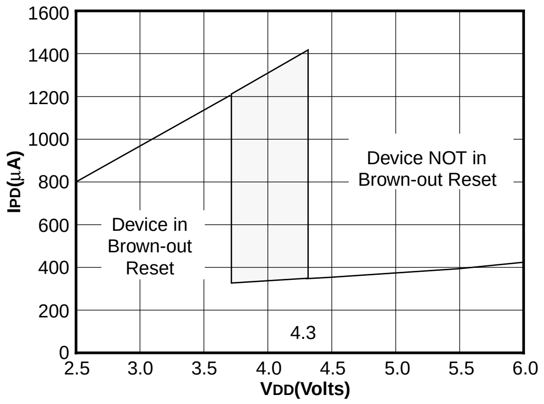
Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 21-8: TYPICAL IPD vs. VDD BROWN-OUT DETECT ENABLED (RC MODE)



The shaded region represents the built-in hysteresis of the brown-out reset circuitry.

FIGURE 21-9: MAXIMUM IPD vs. VDD BROWN-OUT DETECT ENABLED (85°C TO -40°C, RC MODE)



The shaded region represents the built-in hysteresis of the brown-out reset circuitry.

FIGURE 21-10: TYPICAL IPD vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, RC MODE)

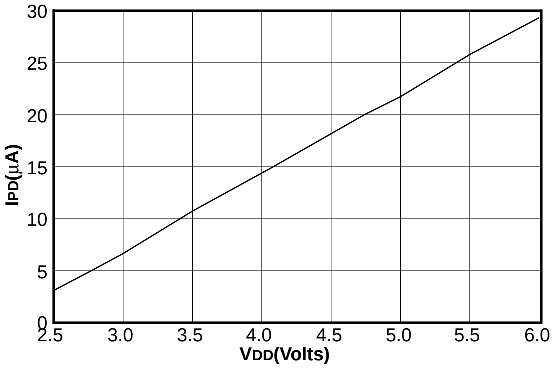
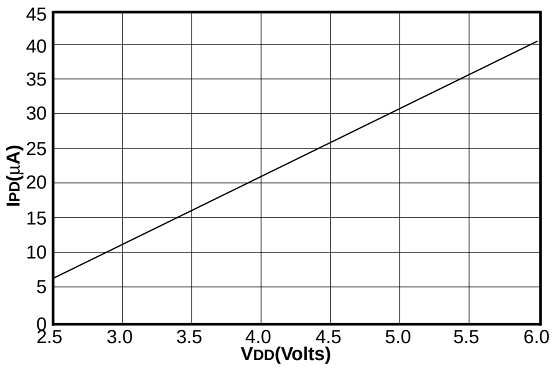


FIGURE 21-11: MAXIMUM IPD vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, 85°C TO -40°C, RC MODE)



Data based on matrix samples. See first page of this section for details.